

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ058N03MS G	**Issued**	17. February 2022
MA#	MA005699159		
Package	PG-TSDSON-8-2	**Weight***	38.23 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	2.82	2.82	28161	28161
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		219	
	non noble metal	iron	7439-89-6	0.168	0.44		4386	
	non noble metal	copper	7440-50-8	6.808	17.81	18.28	178094	182754
wire	non noble metal	copper	7440-50-8	0.043	0.11	0.11	1136	1136
encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		920	
	plastics	epoxy resin	-	1.811	4.74		47372	
	inorganic material	silicondioxide	60676-86-0	15.735	41.16	45.99	411636	459928
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10128	10128
plating	noble metal	silver	7440-22-4	0.963	2.52	2.52	25182	25182
solder	non noble metal	tin	7440-31-5	0.026	0.07		685	
	noble metal	silver	7440-22-4	0.033	0.09		856	
	non noble metal	lead	7439-92-1	1.250	3.27	3.43	32695	34236
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3948	
	non noble metal	copper	7440-50-8	6.127	16.03	16.44	160291	164485
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			28	
	non noble metal	zinc	7440-66-6	0.004	0.01		113	
	non noble metal	iron	7439-89-6	0.086	0.23		2256	
	non noble metal	copper	7440-50-8	3.501	9.16	9.40	91593	93990
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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